

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D.C. 20231 www.uspto.gov

	APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
	09/853,233	05/11/2001	Steven T. Harshfield	MICS:0061	5984	
	7:	590 02/18/2003		•		
	Michael G. Fletcher Fletcher, Yoder & Van Someren P.O. Box 692289			EXAMINER		
				COLEMAN, V	DLEMAN, WILLIAM D	
	Houston, TX	77269-2289		ART UNIT	PAPER NUMBER	
				2823		

DATE MAILED: 02/18/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

RECEIVED

FEB 2 4 2003

Flatcher, Yoder & Van Someren

TECHNOLOGY CENTER 2800

Case transferred to Tom D'amies

PTO-90C (Rev. 07-01)

Art Unit: 2823

#### DETAILED ACTION

1. The indicated allowability of claims 8-16 is withdrawn in view of the newly discovered reference(s) to Kozicki et al., U.S. Publication No.: US 2002/0168820 A1. Rejections based on the newly cited reference(s) follow.

#### Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in-
- (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effect under this subsection of a national application published under section 122(b) only if the international application designating the United States was published under Article 21(2)(a) of such treaty in the English language; or
- (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that a patent shall not be deemed filed in the United States for the purposes of this subsection based on the filing of an international application filed under the treaty defined in section 351(a).
- 3. Claims 1, 2, 3, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 20, 21, 23, 24, 25, 26, 28, 29, 30, 31, 32, 33, 35, 36, 37, 38, 39, 40, 42, 43 and 44 are rejected under 35 U.S.C. 102(e) as being anticipated by Kozicki et al., U.S. Patent Application Publication No.: US 2002/0168820 A1.
- 4. <u>Kozicki</u> discloses a semiconductor device as claimed. See FIGS. 1-29.
- 5. Pertaining to claims 1, 8, 11 and 16 Kozicki teaches a memory cell comprising: a first line 100 formed over a substrate, the first line being formed of a first conductive material (i.e., tungsten, nickel, molybdenum, platinum or metal silicides);
- a layer of a second conductive material 160 disposed over the first line, the second conductive

Art Unit: 2823

material being different from the first conductive material (silver iodide);
a layer of chalcogenide material 140 disposed over the layer of the second conductive

material; and

a second line 120 formed over the layer of chalcogenide material.

6. Pertaining to claims 2 and 32, <u>Kozicki</u> teaches the memory cell, as set forth in claim 1, wherein the first line is embedded in the substrate.

Pertaining to claims 3 and 33, <u>Kozicki</u> teaches the memory cell, as set forth in claim 1, wherein the first line is disposed in a window formed in a dielectric layer **150** disposed over the substrate.

- 7. Pertaining to claims 5 and 12, <u>Kozicki</u> teaches the memory cell, as set forth in claim 1, wherein the layer of a second conductive material is deposited on the first line using an immersion plating technique (please note that there is no patentable weight given to the process since these are product by process claims and only the product will be examined).
- 8. Pertaining to claims 6 and 13, <u>Kozicki</u> teaches the memory cell as set forth in claim 1, wherein the second conductive material comprises at lest one of silver and gold.
- 9. Pertaining to claims 7 and 20, <u>Kozicki</u> teaches the memory cell as set forth in claim 1, wherein the chalcogenide material comprises germanium selenide having ions of the second conductive material therein.
- 10. Pertaining to claim 9, <u>Kozicki</u> teaches the memory cell as set forth in claim 8, wherein the first line is embedded in the substrate.

Art Unit: 2823

11. Pertaining to claim 17, <u>Kozicki</u> teaches the memory cell, as set forth in claim 16, wherein the first line is embedded in the substrate.

- 12. Pertaining to claim 18, Kozicki teaches the memory cell, as set forth in claim 16, wherein the first line is disposed in a window formed in a dielectric layer disposed over the substrate.
- 13. Pertaining to claims 21, 24 and 25, <u>Kozicki</u> teaches a memory cell comprising: a first layer of dielectric material disposed over a substrate, the first layer of dielectric

material having a first window therein;

a first line disposed in the first window, the first line being formed of a first conductive

material that comprises one of aluminum, copper, nickel and tungsten;
a second layer of dielectric material disposed over the first layer of dielectric
material and

over the first line, the second layer of dielectric material having a second window therein, the second window exposing at least a portion of the first line;

layer of a second conductive material disposed in the second window over the first line, the second conductive material being different from the first conductive material;

layer of chalcogenide material disposed in the second window over the layer of the

second conductive material; and second line formed over the layer of chalcogenide material.

Art Unit: 2823

14. Pertaining to claim 23, <u>Kozicki</u> teaches the memory cell, as set forth in claim 2 1, wherein the layer of a second

conductive material is deposited on the first line using an immersion plating technique.

15. Pertaining to claims 26 and 29, <u>Kozicki</u> teaches a memory cell comprising:

a first layer of dielectric material disposed over a substrate, the first layer of dielectric material having a first window therein; a first line disposed in the first window, the first line being formed of a first conductive material that comprises one of aluminum, copper, nickel and tungsten;

a second layer of dielectric material disposed over the first layer of dielectric material and over the first line;

first layer of conductive material disposed over the second layer of dielectric material, the first layer of conductive material; and the second layer of dielectric material having a second window therein, the second window exposing at least a portion of the first line;

a layer of a second conductive material disposed in the second window over the first line, the second conductive material being different from the first conductive material;

a layer of chalcogenide material disposed in the second window over the layer of the

second conductive material that comprises one of aluminum, copper, nickel and tungsten; and

Art Unit: 2823

a second line formed over the layer of chalcogenide material and over the first layer of conductive material.

16. Pertaining to claim 28, <u>Kozicki</u> teaches the memory cell, as set forth in claim 26, wherein the layer of a second

conductive material is deposited on the first line using an immersion plating technique.

- 17. Pertaining to claim 30, Kozicki teaches the memory cell, as set forth in claim 26, wherein the chalcogenide material comprises germanium slenide having ions of the second conductive material therin.
- 18. Pertaining to claim 31, <u>Kozicki</u> teaches a memory comprising:
  a memory array having a plurality of memory cells, each of the memory cells
  comprising:

a first line formed over a substrate, the first line being formed of a first conductive

material that comprises one of aluminum, copper, nickel and tungsten; a layer of a second conductive material disposed over the first line, the second conductive material being different from the first conductive material; a layer of chalcogenide disposed over the layer of the second conductive material;

and a second line formed over the layer of chalcogenide.

19. Pertaining to claim 32, <u>Kozicki</u> teaches the memory cell, as set forth in claim 3 1, wherein the first line is embedded in the substrate.

Art Unit: 2823

- 20. Pertaining to claim 33, <u>Kozicki</u> teaches the memory cell, as set forth in claim 31, wherein the first line is disposed in a window formed in a dielectric layer disposed over the substrate.
- 21. Pertaining to claim 35, <u>Kozicki</u> teaches the memory cell, as set forth in claim 31, wherein the layer of a second conductive material is deposited on the first line using an immersion plating technique.
- 22. Pertaining to claim 38, <u>Kozicki</u> teaches an electronic device comprising:

  a processor; a memory operatively coupled to the processor, the memory
  comprising a memory array having a plurality of memory cells, each of the memory cells
  comprising:
- a first line formed over a substrate, the first line being formed of a first conductive material that comprises one of aluminum, copper, nickel and tungsten; a layer of a second conductive material disposed over the first line, the second conductive material being different from the first conductive material;
- a layer of chalcogenide disposed over the layer of the second conductive material;
  - a second line formed over the layer of chalcogenide.
- 23. Pertaining to claim 39, <u>Kozicki</u> teaches the memory cell, as set forth in claim 38, wherein the first line is embedded in the substrate.
- 24. Pertaining to claim 40, <u>Kozicki</u> teaches the memory cell, as set forth in claim 38, wherein the first line is disposed in a window formed in a dielectric layer disposed over the substrate.

Art Unit: 2823

Page 8

25. Pertaining to claim 42, <u>Kozicki</u> teaches the memory cell, as set forth in claim 38,

wherein the layer of a second conductive material is deposited on the first line using an

immersion plating.

**Objections** 

26. Claim 14 is objected to as being dependent upon a rejected base claim, but would

be allowable if rewritten in independent form including all of the limitations of the base

claim and any intervening claims.

Conclusion

27. Any inquiry concerning this communication or earlier communications from the

examiner should be directed to W. David Coleman whose telephone number is 703-305-

0004. The examiner can normally be reached on 9:00 AM-5:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Olik Chaudhuri can be reached on 703-306-2794. The fax phone numbers for

the organization where this application or proceeding is assigned are 703-308-7722 for

regular communications and 703-308-7721 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the receptionist whose telephone number is 703-308-

0956.

W. David Coleman

Examiner

Art Unit 2823

WDC

February 13, 2003

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FORM PTO-1449 (modified)	atty. Docket no.	SERIAL NO.	85 E
	MICS:0061/FLE (00-0535)	Unassigned	 ක ක
List of Patents and Publications For Applicant's Information	APPLICANT		60 60 60 60 60 60 60 60 60 60 60 60 60 6
Disclosure Statement	Steven T. Harshfield et al.		971 09/
Use several sheets if necessary)	FILING DATE	GROUP	36
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#### FOREIGN PATENT DOCUMENTS

EXAM. INIT.	REF. DES.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION

#### OTHER ART

		(Author, Title, Journal, Volume, Pertinent Pages, & Date)
00	1	Jacques Coderre; Electroless Ni/Au and Process Control; Process Control; Printed Circuit Fabrication 1978-1998; pgs. 42-46.
8	2	Don Cullen; Electroless Nickel/Immersion Gold; Ni/Au; Printed Circuit Fabrication 1978-1998; pgs. 32-39.
0	3	Jean W. Chevaiier; Electroless Gold Plating; pgs. 323-325.
EXAMINER WILL DATE CONSIDERED 3/13/83		
EXAMINI	ER: Initi	ial if reference considered, whether or not citation is in conformance with MPEP609; Draw line through citation

not in conformance and not considered. Include copy of this form with next communication to applicant.

Information Disclosure Statement--PTO-1449 (Modified)



## Attachment for PTO-948 (Rev. 03/01, or earlier) 6/18/01

The below text replaces the pre-printed text under the heading, "Information on How to Effect Drawing Changes," on the back of the PTO-948 (Rev. 03/01, or earlier) form.

### INFORMATION ON HOW TO EFFECT DRAWING CHANGES

#### 1. Correction of Informalities - 37 CFR 1.85

New corrected drawings must be filed with the changes incorporated therein. Identifying indicia, if provided, should include the title of the invention, inventor's name, and application number, or docket number (if any) if an application number has not been assigned to the application. If this information is provided, it must be placed on the front of each sheet and centered within the top margin. If corrected drawings are required in a Notice of Allowability (PTOL-37), the new drawings MUST be filed within the THREE MONTH shortened statutory period set for reply in the Notice of Allowability. Extensions of time may NOT be obtained under the provisions of 37 CFR 1.136(a) or (b) for filing the corrected drawings after the mailing of a Notice of Allowability. The drawings should be filed as a separate paper with a transmittal letter addressed to the Official Draftsperson.

## 2. Corrections other than Informalities Noted by Draftsperson on form PTO-948.

All changes to the drawings, other than informalities noted by the Draftsperson, MUST be made in the same manner as above except that, normally, a highlighted (preferably red ink) sketch of the changes to be incorporated into the new drawings MUST be approved by the examiner before the application will be allowed. No changes will be permitted to be made, other than correction of informalities, unless the examiner has approved the proposed changes.

#### **Timing of Corrections**

Applicant is required to submit the drawing corrections within the time period set in the attached Office communication. See 37 CFR 1.85(a).

Failure to take corrective action within the set period will result in ABANDONMENT of the application.

REVIEWER Draftsman: Son Lam DATE 02 13 03 TELEPHONE NO. \_\_\_\_\_\_\_

# Application/Control No. O9/853,233 References Cited Application/Control No. O9/853,233 Examiner W. David Coleman Applicant(s)/Patent Under Reexamination HARSHFIELD ET AL. Page 1 of Section Page 1 of Secti

#### U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-2002/0168820	11-2002	Kozicki et al.	438/259
	В	US-			
	С	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	Н	US-			
	1	US-			
	J	US-			
	к	US-			
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#### FOREIGN PATENT DOCUMENTS

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#### NON-PATENT DOCUMENTS

	ISOIS-FAI EIST DOCUMENTS						
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.